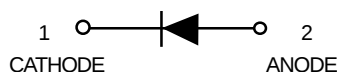


Switching Diode



BAS16HT1



CASE 477- 02, STYLE 1
SOD- 323

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V_R	75	Vdc
Peak Forward Current	I_F	200	mAdc
Peak Forward Surge Current	$I_{FM}(\text{surge})$	500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board,* $T_A = 25^\circ\text{C}$	P_D	200	mW
Derate above 25°C		1.57	mW/ $^\circ\text{C}$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	635	$^\circ\text{C/W}$
Junction and Storage Temperature	T_J, T_{stg}	150	$^\circ\text{C}$

**FR-4 Minimum Pad

DEVICEMARKING

BAS16HT1 = A6

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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OFF CHARACTERISTICS

Reverse Voltage Leakage Current ($V_R = 75 \text{ Vdc}$) ($V_R = 75 \text{ Vdc}, T_J = 150^\circ\text{C}$) ($V_R = 25 \text{ Vdc}, T_J = 150^\circ\text{C}$)	I_R	—	1.0 50 30	μAdc
Reverse Breakdown Voltage ($I_{BR} = 100 \mu\text{Adc}$)	$V_{(BR)}$	75	—	Vdc
Forward Voltage ($I_F = 1.0 \text{ mAdc}$) ($I_F = 10 \text{ mAdc}$) ($I_F = 50 \text{ mAdc}$) ($I_F = 150 \text{ mAdc}$)	V_F	—	715 855 1000 1250	mV
Diode Capacitance ($V_R = 0, f = 1.0 \text{ MHz}$)	C_D	—	2.0	pF
Forward Recovery Voltage ($I_F = 10 \text{ mAdc}, t_r = 20 \text{ ns}$)	V_{FR}	—	1.75	Vdc
Reverse Recovery Time ($I_F = I_R = 10 \text{ mAdc}, R_L = 50 \Omega$)	t_{rr}	—	6.0	ns
Stored Charge ($I_F = 10 \text{ mAdc}$ to $V_R = 5.0 \text{ Vdc}, R_L = 500 \Omega$)	Q_s	—	45	pC

- Figure 1. Recovery Time Equivalent Test Circuit**

The graph shows the relationship between forward current (I_F) and forward voltage (V_F) for a diode at three different ambient temperatures (T_A):

- $T_A = 85^\circ\text{C}$ (Top curve)
- $T_A = 25^\circ\text{C}$ (Middle curve)
- $T_A = -40^\circ\text{C}$ (Bottom curve)

As the ambient temperature increases, the forward current for a given forward voltage also increases.

Figure 2. Forward Voltage

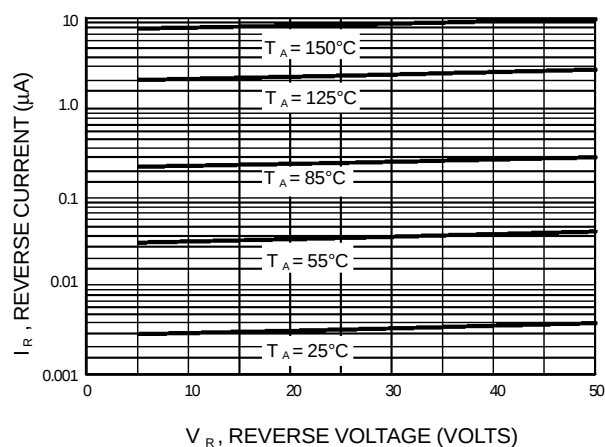


Figure 3. Leakage Current

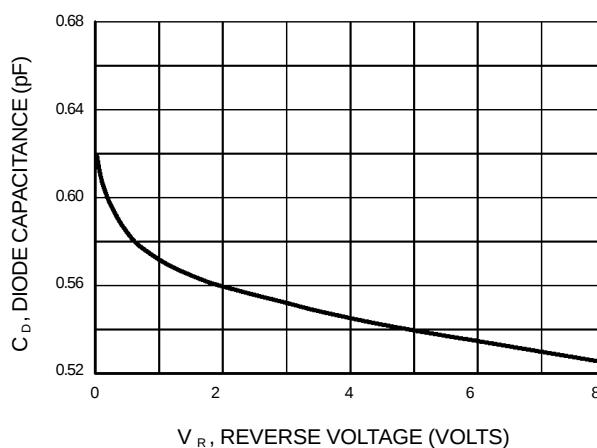


Figure 4. Capacitance